Layer Name	Туре	Material	Thickness (mm)	Color	Epsilon R	Loss Tangent
F.Silkscreen	Top Silk Screen	Direct Printing	0 mm	White	1	0
F.Paste	Top Solder Paste		0 mm		1	0
F.Mask	Top Solder Mask	Dry Film	0.01 mm	Green	3.3	0
F.Cu	copper		0.035 mm		1	0
Dielectric 1	core	FR4	1.51 mm		4.5	0.02
B.Cu	copper		0.035 mm		1	0
B.Mask	Bottom Solder Mask	Dry Film	0.01 mm	Green	3.3	0
B.Paste	Bottom Solder Paste		0 mm		1	0
B.Silkscreen	Bottom Silk Screen	Direct Printing	0 mm	White	1	0

		REVISION HISTORY			
ZONE	REV	DESCRIPTION	DATE	APPROVED	1
	V1R0	First version	2022-04-03]
]/
					1
					1

BOARD CHARACTERISTICS

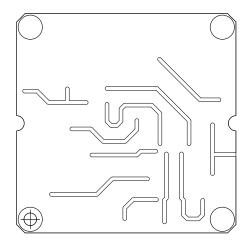
Copper Layer Count: 2 Board Thickness: 1.6000 mm

Board overall dimensions: 58.0500 mm x 58.0500 mm

Min track/spacing: 1.0000 mm / 0.1000 mm Min hole diameter: 0.3000 mm

Copper Finish: Immersion gold Impedance Control: No Castellated pads: No Plated Board Edge: No

Edge card connectors: No



STATUS	TECHNICAL REFERENCE	STANDARD	LICENSE	SIZE	
Prototype	IRM-03-05	IS07200-2004	CC BY-SA	A4	
PART NUMBER	PCB NUMBER	ASSEMBLY NUMBER	ID	SCALE	
AE01.07.50.100	-	-	-	1:1	
SHEET NAME		FILE AE01.07.50.100.kicad_pcb			

DESCRIPTION 230Vac input. 5Vdc/600mA/3W output. European outlet size.		astroelectronic@		AE
TITLE IRM-03-05 AC/DC PO		VER./REV. V1R0	DATE 2022-04-03	SHEET 1/1
	KiCad E.D.A. kicad 6.0.4−6f	826c9f\$5~	·116~ubuntu18	.04.1